

ABSTRACT OF THE DISCLOSURE

SHEET FOR SEALING HOLLOW ELECTRONIC DEVICE, METHOD FOR PRODUCING HOLLOW ELECTRONIC DEVICE PACKAGE, AND HOLLOW ELECTRONIC DEVICE PACKAGE

It is an object of the present invention to provide a sheet for sealing a hollow electronic device which can suppress variation among packages in the amount of a resin entering into a hollow part between an electronic device and an adherend. This object is achieved by a sheet for sealing a hollow electronic device, wherein a time T from start of the measurement of storage modulus of a sample until the storage modulus reaches 10 MPa is 400 seconds or less.

FIG. 1